

TMDS62LEVM Design Package Content Overview



TMDS62LEVM_Download_Files List document lists names of the folders and file names in the folders along with the format for all the files that have been included in the TMDS62LEVM (for both ORCAD + ALLEGRO based design and ALTIUM based design).

The TMDS62LEVM evaluation module (EVM) is designed for low-cost and performance optimized AM62L family of application processors. TMDS62LEVM evaluation module is built around AM62L processor (11.9mm × 11.9mm, 0.5mm VCA, 373-pin FCCSP BGA package (ANB)), scalable Arm® Cortex®-A53 core performance and embedded features such as: Multimedia DSI support, integrated ADC on chip, advanced lower power management modes, and extensive security options for IP protection and secure boot. The product overview document is available on TMDS62LEVM product folder on TI.com for customer to review before downloading the single Zip folder.

Table 1. Proc181E1-1 Orcad + Allegro

FOLDER (1st Level)	FOLDER (2nd Level)	Files Inside	File Type
----	----	PROC181E1-1_Folders_Files_List	XLS
1_SCHEMATIC	1_ORCAD	PROC181E1-1_SCH_With_Design_Updates..Notes_V1.0	PDF
	2_PDF_Standard	PROC181E1-1_SCH_With_Design_Updates..Notes_V1.0	PDF
	3_PDF_Intelligent	PROC181E1-1_SCH_With_Design_Updates..Notes_V1.0	DSN
2_BOM	----	PROC181E1-1_BOM	XLS
3_Board_File	Allegro	PROC181E1-1_BRD	BRD
	Simulation Scorecard	TMDS62LEVM_Simulations_Scorecard	PDF
	Altium_ASCII	PROC181E1-1_BRD	ALG
4_Gerber	ODBGBR	PROC181E1-1_ODBGBR	ZIP
	274X	PROC181E1-1_274XGBR	ZIP
	IPC-D-356_NETLIST	PROC181E1-1_IPC	IPC
5_Gerber_PDF	FAB	PROC181E1-1_FAB	PDF
	PCB LAYERS	PROC181E1-1_ALL_LAYER	PDF
	Gerber Layers	PROC181E1-1_ALL_LAYER	PDF
6_Assembly_Models_Package	2D	PROC181E1-1_DXF_BASY	DXF
		PROC181E1-1_DXF_TASY	DXF
	3D	PROC181E1-1_3D.STEP	STP
		PROC181E1-1_BRD	EMP
	IDF	PROC181E1-1_BRD	EMN
		PROC181E1-1_ASSEMBLY	PDF
	Assembly_Drawing	PROC181E1-1_TASY	PDF
		PROC181E1-1_BASY	PDF
		art_aper + 8 x .ART files	ART
	XY-REP	PROC181E1-1_XY_REP	XLS

Table 1. Proc181E1-1 Orcad + Allegro (continued)

FOLDER (1st Level)	FOLDER (2nd Level)	Files Inside	File Type
7_PCB_LAYER_STACKUP	---	TMDS62LEVM-6L-20-12-2023-[1639]	PDF
8_Power_Supply_Sequencing	---	PROC181E1-1_POWER_SEQUENCE	PDF
9_SysConfig_PinMux_File	---	TMDS62LEVM	syscfg

Table 2. Proc181E1-1 ALTIUM

FOLDER (1st level)	FOLDER (2nd level)	Files Inside	File type
----	----	PROC181E1-1_Folders_Files_List	XLS
1_SCHEMATIC	1_Altium	PROC181E1-1_SCH_With_Design_Updates..Notes_V1.0	.SCHDOC
	2_PDF_Standard	PROC181E1-1_S_SCH_With_Design_Updates..Notes_V1.0	PDF
	3_PDF_Intelligent	PROC181E1-1_I_SCH_With_Design_Updates..Notes_V1.0	PDF
2_BOM	----	PROC181E1-1_BOM	XLS
3_Board_File	Altium	PROC181E1-1_PRJPCB	.PCBDOC .PRJPCB
	Board_pdf_dimensions	PROC181E1-1_BRD	PDF
	Simulation Scorecard	TMDS62LEVM_Simulations_Scorecard	PDF
4_Gerber	ODBGBR	PROC181E1-1_ODBGBR	TGZ
	274X	PROC181E1-1_274XGBR	ZIP
	IPC-D-356_NETLIST	PROC181E1-1_IPCD356	IPC
5_Gerber_PDF	FAB	PROC181E1-1_FAB	PDF
	PCB LAYERS	PROC181E1-1_ALL_LAYER	PDF
	Gerber Layers	PROC181E1-1_ALL_LAYER	PDF
6_Assembly_Models_Package	2D	PROC181E1-1_DXF_BASY	DXF
		PROC181E1-1_DXF_TASY	DXF
	3D	PROC181E1-1_3D.STEP	STP
	IDF	PROC181E1-1_BRD	EMP
		PROC181E1-1_BRD	EMN
	Assembly_Drawing	PROC181E1-1 ASSEMBLY	PDF
		PROC181E1-1_TASY	PDF
		PROC181E1-1_BASY	PDF
	STNL	PROC181E1-1_BRD_11_3 art_aper + 8 x .ART files	ART
	XY-REP	_PROC181E1-1_XY_REPORT	XLS
7_PCB_LAYER_STACKUP	---	TMDS62LEVM-6L-20-12-2023-[1639]	PDF
8_Power_Supply_Sequencing	---	PROC181E1-_POWER_SEQUENCE_IO_DDR.pdf	PDF
		PROC181E1-1_POWER_SEQUENCE_RTC_Only.pdf	PDF
9_3DBOARD_PDF		PROC181E1-1_3DBOARD	PDF

Table 2. Proc181E1-1 ALTIUM (continued)

FOLDER (1st level)	FOLDER (2nd level)	Files Inside	File type
10_Gerber_comparision_ALG _PRJPCB_pdf		PROC181E1-1_gerbet_comparision	PDF
11_Sysyconfig		TMDS62LEVM	.syscfg

References

- [\[FAQ\] AM62L \(AM62L32 , AM62L31 \) Custom board hardware design - Design notes and Review notes for Reuse of EVM TMDS62LEVM Schematics](#)
- [\[FAQ\] AM62L \(AM62L32 , AM62L31 \) Custom board hardware design - Available design files and supported CAD tools format that can be used during custom board Schematic and PCB design](#)

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